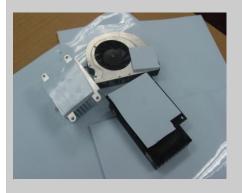


THERMAL CONDUCTIVE GAP FILLER 1.5W/m-K

Features and Benefits

- 1.5W/m-K thermal conductivity
- Exceptional compressibility
- Cost effective
- Naturally tacky
- Electrically isolating
- RoHS compliant
- Halogen-free



Typical Applications

- Notebook and desktop computers
- Memory modules
- Heat pipe assemblies
- HDDs and DVDs
- Flat-panel displays
- Telecommunication hardware

Optional Configurations

• Can be die-cut into specific dimensions

E-Fill 8300 is a ceramic filled silicone elastomer. It is exceptionally soft and is suitable for applications that require moderate thermal performance. The formulation of E-Fill 8300 is designed to be RoHS compliant and halogen-free, providing extra reassurance in applications where hazardous substances are forbidden.

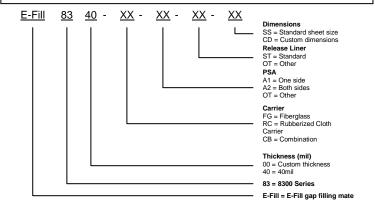
E-Fill 8300 is electrically non-conductive and naturally tacky. Additional adhesive is generally not required.

Properties	Typical Data	Test Method
Construction & Composition	Soft silicone elastomer	_
Color	Blue	Visual
Thickness Range /inch (mm)	0.01"~0.40" (0.254~10.16) in 0.01" (0.254) increments	_
Standard Sheet Size	12" x 16"	_
Density /g.cm ⁻³	1.8	_
Hardness /Shore 00	25	ASTM D2240
UL Flammability Rating	UL94 V0	E109346
Temperature Range /℃	-40~200℃	_
Thermal Conductivity W.m ⁻¹ .K ⁻¹	1.5	ASTM D5470 (modified)
Breakdown Voltage /V	>5000	ASTM D149
Shelf Life	24 months	_

Please contact us for other special requirements

Carrier Treatment	Criteria			
Fiber Glass (FG)	Compulsory for ≤ 0.03" (0.75mm)			
Rubberized Cloth (RC)	Optional to all thickness			
Pressure Sensitive Adhesive (PSA)	Not Recommended			
Detachable Adhesive (DA)	Optional to ≥ 0.039" (1.0mm)			
Aluminum Foil (AL)	Not Recommended			
Kapton (PI)	Not Recommended			
Talc treatment (DAT)	Optional to all thickness			

Product Code and Descriptions



Hong Kong

Tel: (852) 2686 8168 Fax: (852) 2686 8268 E-mail: emeihk@emeigroup.com

Dongguan

(86) 769-8334 1628/3400 (86) 769-8334 2028/5656 emeidg@emeigroup.com

Shanghai

(86) 21-5868 3381 (86) 21-5868 3386 emeish@emeigroup.com

Taiwan

(886) 2-2793 9055 (886) 2-2793 9501 emeitw@emeigroup.com

www.emeigroup.com



THERMAL CONDUCTIVE GAP FILLER 1.5W/m-K

产品特点

- 导热率 1.5W/m-K
- 高压缩比
- 低成本
- 具有天然粘性
- 电绝缘
- 符合 RoHS 规格
- 无卤素



一般应用

- 桌上型电脑及笔记本
- 内存模组
- 热管组件
- HDDs 和 DVDs
- 平板显示器
- 通信用硬件

其他配置

• 可模切成特定尺寸

E-Fill 8300 是一种使用陶瓷填充物料的硅树脂弹性体。E-Fill 8300 十分柔 软,适合低压力应用,而且配方符合 RoHS 规格更达到无卤素要求,令客户 在使用时对于有害物质的控制更有信心。

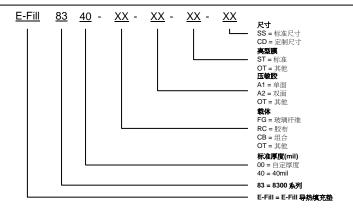
Fill 8300 具有电绝缘及天然粘性等特点,在正常情况下不需要增加额外的 胶粘剂。

一般特性	E-Fill 8300 系列	测试方法
结构及主要成分	硅树脂弹性体	_
颜色	蓝色	目测
厚度 /inch (mm)	0.01"~0.40" (0.254~10.16) 以 0.01" (0.254)为基本增量单位	_
标准片材尺寸	12" x 16"	_
密度 /g.cm ⁻³	1.8	_
硬度 /Shore 00	25	ASTM D2240
UL 燃烧等级	UL94 V0	E109346
使用温度 /℃	-40~200°C	_
导热率 W.m ⁻¹ .K ⁻¹	1.5	ASTM D5470 (modified)
击穿电压/V	>5000	ASTM D149
有效期	24 months	_
如对产品有特殊要求,请联络我们		

如对产品有特殊要求,请联络获制

载体	标准
玻璃纤维 (FG)	厚度 ≤ 0.03" (0.75mm)必 须使用
胶布 (RC)	可供任何厚度使用
压敏胶 (PSA)	不建议使用
不粘胶 (DA)	厚度≥ 0.039" (1.0mm) 可 使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	可供任何厚度使用

产品编码及描叙



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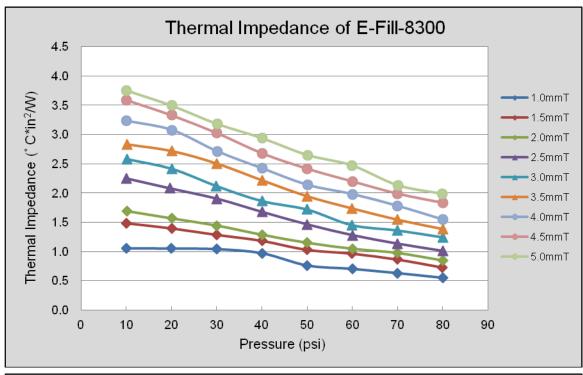
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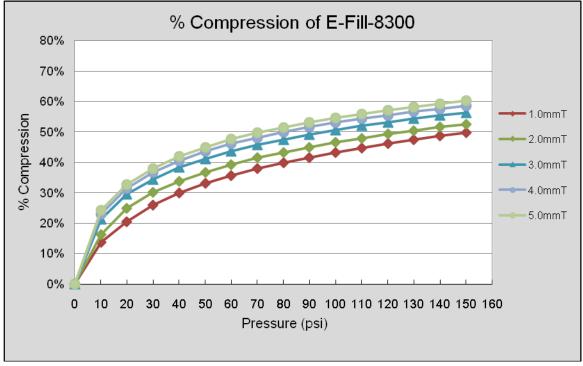
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